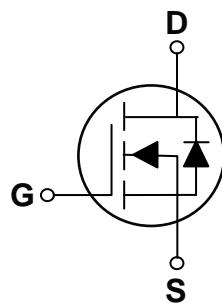
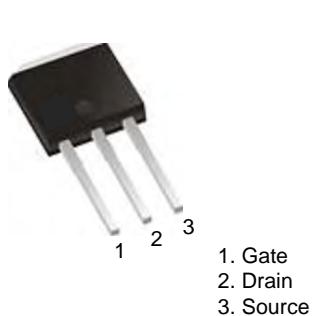


## 60V N-Channel MOSFETs

### General Description

These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

### TO-251 Pin Configuration



BVDSS	RDS(ON)	ID
60V	34mΩ	25A

### Features

- 60V, 25A, RDS(ON)=34mΩ @ VGS = 10V
- Improved dv/dt capability
- Fast switching
- 100% EAS Guaranteed
- Green Device Available

### Applications

- Motor Drive
- Power Tools
- LED Lighting

### Absolute Maximum Ratings (Tc=25°C unless otherwise noted)

Symbol	Parameter	Rating	Units
V <sub>DS</sub>	Drain-Source Voltage	60	V
V <sub>GS</sub>	Gate-Source Voltage	± 20	V
I <sub>D</sub>	Drain Current – Continuous (T <sub>c</sub> =25 °C)	25	A
	Drain Current – Continuous (T <sub>c</sub> =100 °C)	16	A
I <sub>DM</sub>	Drain Current – Pulsed <sup>1</sup>	100	A
EAS	Single Pulse Avalanche Energy <sup>2</sup>	24	mJ
IAS	Single Pulse Avalanche Current <sup>2</sup>	22	A
P <sub>D</sub>	Power Dissipation (T <sub>c</sub> =25 °C)	40	W
	Power Dissipation – Derate above 25 °C	0.32	W/°C
T <sub>STG</sub>	Storage Temperature Range	-50 to 150	°C
T <sub>J</sub>	Operating Junction Temperature Range	-50 to 150	°C

### Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
R <sub>θJA</sub>	Thermal Resistance Junction to ambient	---	62	°C/W
R <sub>θJC</sub>	Thermal Resistance Junction to Case	---	3.1	°C/W



# FTK6908I

## 60V N-Channel MOSFETs

Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)

### Off Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}$ , $I_D=250\mu\text{A}$	60	---	---	V
$\Delta BV_{DSS}/\Delta T_J$	$BV_{DSS}$ Temperature Coefficient	Reference to $25^\circ\text{C}$ , $I_D=1\text{mA}$	---	0.07	---	$\text{V}/^\circ\text{C}$
$I_{DSS}$	Drain-Source Leakage Current	$V_{DS}=60\text{V}$ , $V_{GS}=0\text{V}$ , $T_J=25^\circ\text{C}$	---	---	1	$\mu\text{A}$
		$V_{DS}=48\text{V}$ , $V_{GS}=0\text{V}$ , $T_J=125^\circ\text{C}$	---	---	10	$\mu\text{A}$
$I_{GSS}$	Gate-Source Leakage Current	$V_{GS}=\pm 20\text{V}$ , $V_{DS}=0\text{V}$	---	---	$\pm 100$	$\text{nA}$

### On Characteristics

$R_{DS(\text{ON})}$	Static Drain-Source On-Resistance	$V_{GS}=10\text{V}$ , $I_D=15\text{A}$	---	28	34	$\text{m}\Omega$
		$V_{GS}=4.5\text{V}$ , $I_D=10\text{A}$	---	33	40	$\text{m}\Omega$
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{GS}=V_{DS}$ , $I_D=250\mu\text{A}$	1.2	1.7	2.5	V
			---	-4.6	---	$\text{mV}/^\circ\text{C}$
$g_{fs}$	Forward Transconductance	$V_{DS}=10\text{V}$ , $I_D=8\text{A}$	---	8	---	S

### Dynamic and switching Characteristics

$Q_g$	Total Gate Charge <sup>2,3</sup>	$V_{DS}=30\text{V}$ , $V_{GS}=10\text{V}$ , $I_D=20\text{A}$	---	16.6	24	nC
$Q_{gs}$	Gate-Source Charge <sup>2,3</sup>		---	2.2	4.4	
$Q_{gd}$	Gate-Drain Charge <sup>2,3</sup>		---	3.9	8	
$T_{d(on)}$	Turn-On Delay Time <sup>2,3</sup>	$V_{DD}=30\text{V}$ , $V_{GS}=10\text{V}$ , $R_G=6\Omega$	---	4.6	9	ns
$T_r$	Rise Time <sup>2,3</sup>		---	14.8	28	
$T_{d(off)}$	Turn-Off Delay Time <sup>2,3</sup>		---	27.2	52	
$T_f$	Fall Time <sup>2,3</sup>		---	7.8	15	
$C_{iss}$	Input Capacitance		---	1180	1720	pF
$C_{oss}$	Output Capacitance	$V_{DS}=30\text{V}$ , $V_{GS}=0\text{V}$ , $F=1\text{MHz}$	---	68	100	
$C_{rss}$	Reverse Transfer Capacitance		---	45	70	
$R_g$	Gate resistance	$V_{GS}=0\text{V}$ , $V_{DS}=0\text{V}$ , $F=1\text{MHz}$	---	2.1	4.2	$\Omega$

### Drain-Source Diode Characteristics and Maximum Ratings

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$I_s$	Continuous Source Current	$V_G=V_D=0\text{V}$ , Force Current	---	---	25	A
			---	---	100	A
$I_{SM}$	Pulsed Source Current					
$V_{SD}$	Diode Forward Voltage	$V_{GS}=0\text{V}$ , $I_s=1\text{A}$ , $T_J=25^\circ\text{C}$	---	---	1	V
$t_{rr}$	Reverse Recovery Time <sup>2</sup>	$V_{GS}=0\text{V}$ , $I_s=1\text{A}$ , $dI/dt=100\text{A}/\mu\text{s}$	---	17	---	ns
$Q_{rr}$	Reverse Recovery Charge <sup>2</sup>	$T_J=25^\circ\text{C}$	---	12	---	nC

Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2.  $V_{DD}=25\text{V}$ ,  $V_{GS}=10\text{V}$ ,  $L=0.1\text{mH}$ ,  $I_{AS}=22\text{A}$ ,  $R_G=25\Omega$ , Starting  $T_J=25^\circ\text{C}$
3. The data tested by pulsed, pulse width  $\leq 300\text{us}$ , duty cycle  $\leq 2\%$ .
4. Essentially independent of operating temperature.

## 60V N-Channel MOSFETs

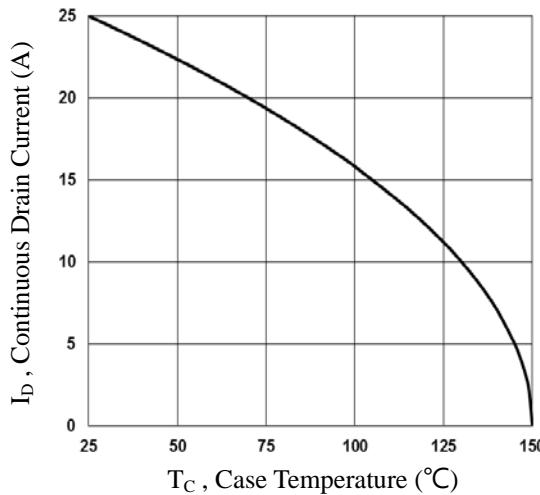


Fig.1 Continuous Drain Current vs.  $T_C$

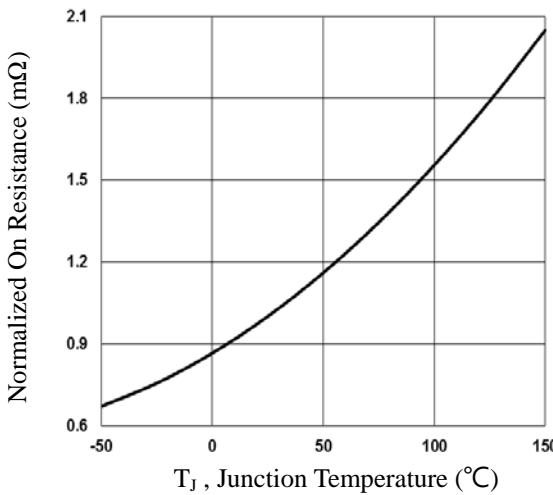


Fig.2 Normalized RDS(on) vs.  $T_J$

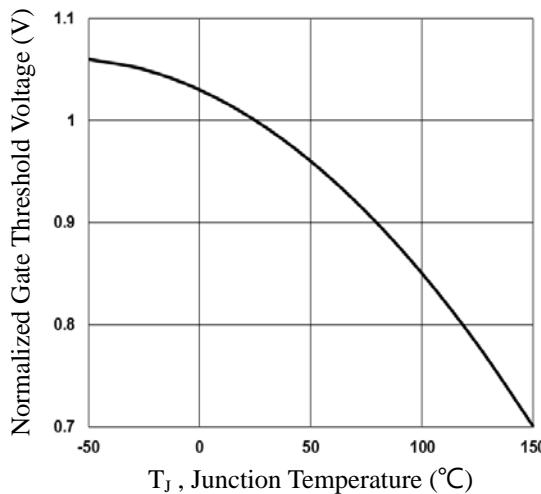


Fig.3 Normalized  $V_{th}$  vs.  $T_J$

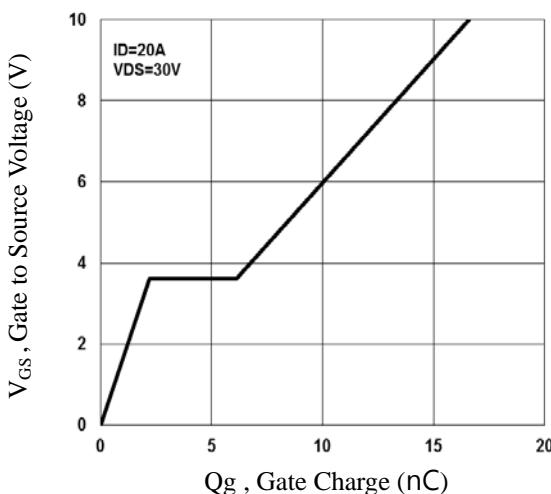


Fig.4 Gate Charge Waveform

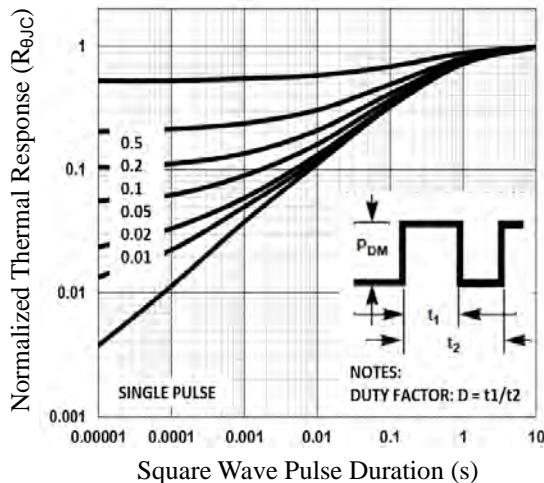


Fig.5 Normalized Transient Impedance

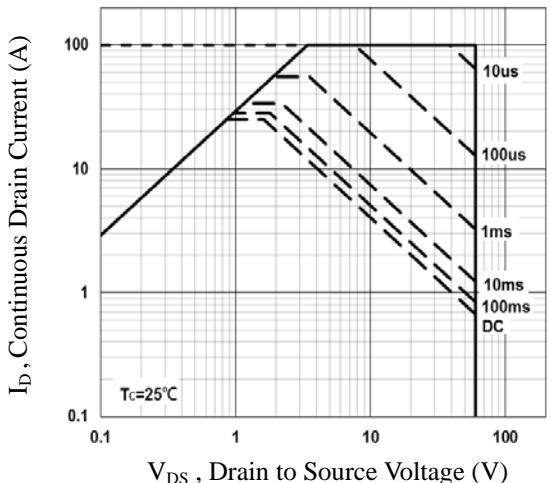


Fig.6 Maximum Safe Operation Area

## 60V N-Channel MOSFETs

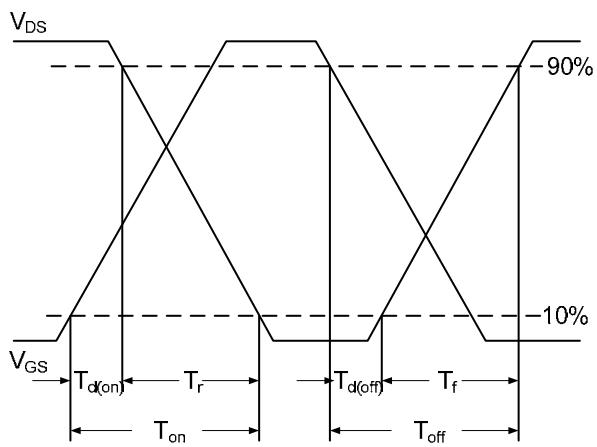


Fig.7 Switching Time Waveform

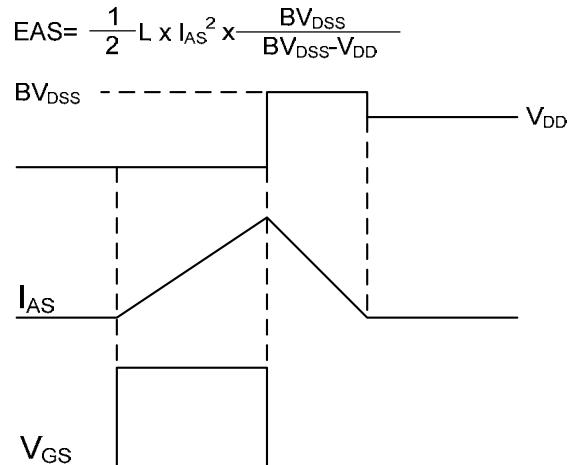
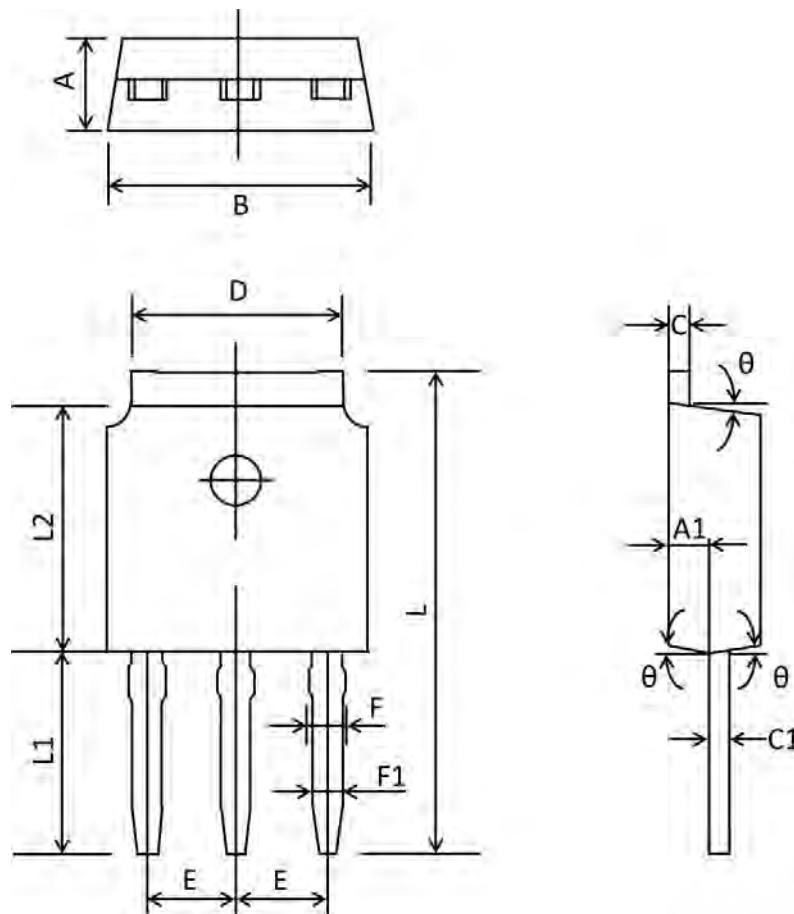


Fig.8 EAS Waveform

## 60V N-Channel MOSFETs

### TO-251 PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	2.20	2.40	0.087	0.094
A1	0.91	1.11	0.036	0.044
B	6.50	6.70	0.256	0.264
C	0.46	0.580	0.018	0.230
C1	0.46	0.580	0.018	0.030
D	5.10	5.46	0.201	0.215
E	2.186	2.386	0.086	0.094
F	0.74	0.94	0.029	0.037
F1	0.660	0.860	0.026	0.034
L	11.70	12.30	0.461	0.484
L1	4.8	5.2	0.189	0.205
L2	6.00	6.20	0.236	0.244
θ	3°	9°	3°	9°